CHIP SCALE PACKAGING WITH MULTI-LAYER FLIP CHIP ARRANGEMENT AND BALL GRID ARRAY INTERCONNECTION

ABSTRACT

In accordance with the objectives of the invention a new package is provided that is provided with a cavity that is shaped such that more than one semiconductor device can in a vertical direction be mounted in the cavity of the package. The devices that are mounted inside the cavity of the package are separated by separate components of insulation, the overlying devices are electrically interconnected by horizontally positioned solder bumps and vertical interconnect plugs.

Fig. 1